

DATA SHEET

BYC5-600

Rectifier diode

ultrafast, low switching loss

Product specification

March 2001



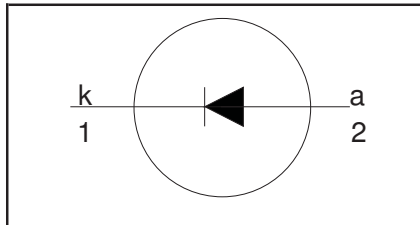
Rectifier diode ultrafast, low switching loss

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FEATURES

- Extremely fast switching
- Low reverse recovery current
- Low thermal resistance
- Reduces switching losses in associated MOSFET

SYMBOL



QUICK REFERENCE DATA

$V_R = 600\text{ V}$
$V_F \leq 1.75\text{ V}$
$I_{F(AV)} = 5\text{ A}$
$t_{rr} = 19\text{ ns (typ)}$

APPLICATIONS

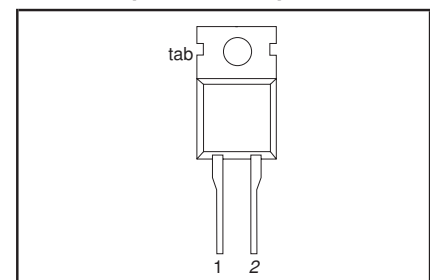
- Active power factor correction
- Half-bridge lighting ballasts
- Half-bridge/ full-bridge switched mode power supplies.

The BYC5-600 is supplied in the SOD59 (TO220AC) conventional leaded package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode
tab	cathode

SOD59 (TO220AC)



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	Peak repetitive reverse voltage		-	600	V
V_{RWM}	Crest working reverse voltage		-	600	V
V_R	Continuous reverse voltage		-	500	V
$I_{F(AV)}$	Average forward current	$T_{mb} \leq 110\text{ °C}$ $\delta = 0.5$; with reappplied $V_{RRM(max)}$;	-	5	A
I_{FRM}	Repetitive peak forward current	$T_{mb} \leq 89\text{ °C}$ $\delta = 0.5$; with reappplied $V_{RRM(max)}$;	-	10	A
I_{FSM}	Non-repetitive peak forward current.	$T_{mb} \leq 89\text{ °C}$ $t = 10\text{ ms}$ $t = 8.3\text{ ms}$ sinusoidal; $T_j = 150\text{ °C}$ prior to surge with reappplied $V_{RWM(max)}$	-	40 44	A A
T_{stg}	Storage temperature		-40	150	°C
T_j	Operating junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j-mb}$	Thermal resistance junction to mounting base		-	-	2.5	K/W
$R_{th\ j-a}$	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

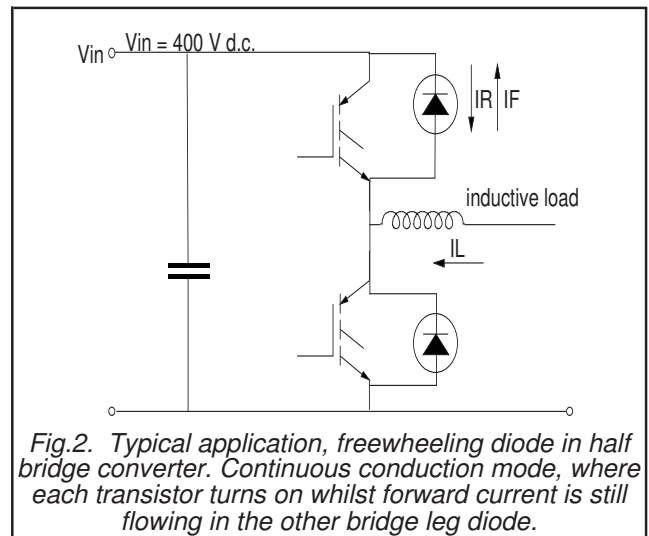
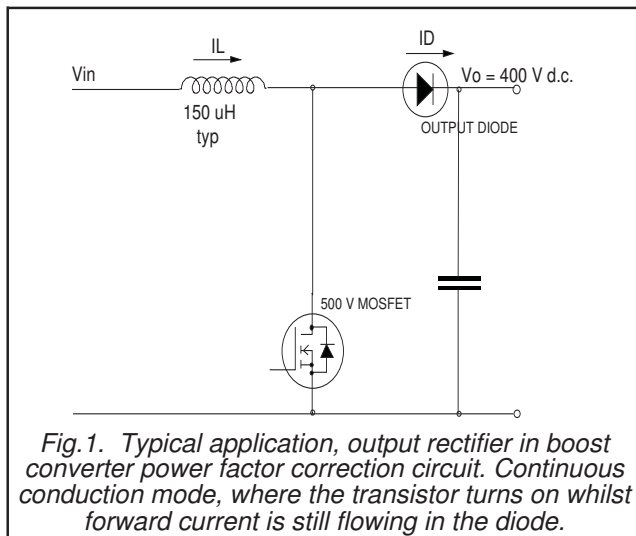
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ELECTRICAL CHARACTERISTICS

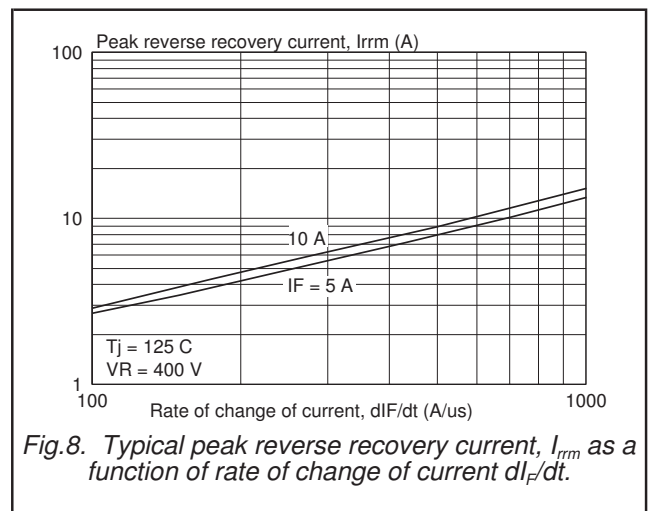
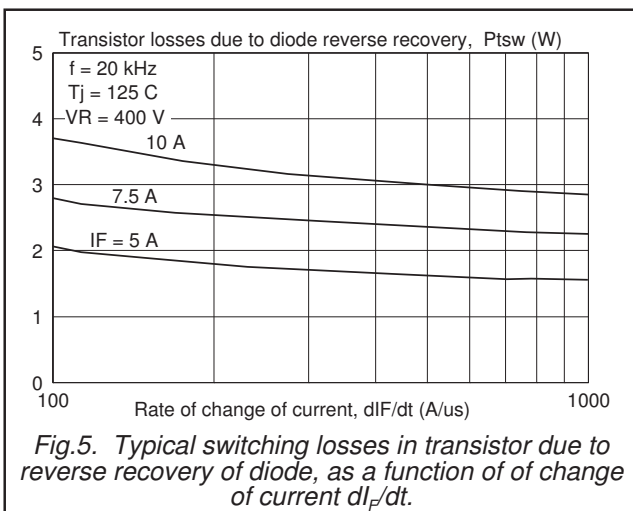
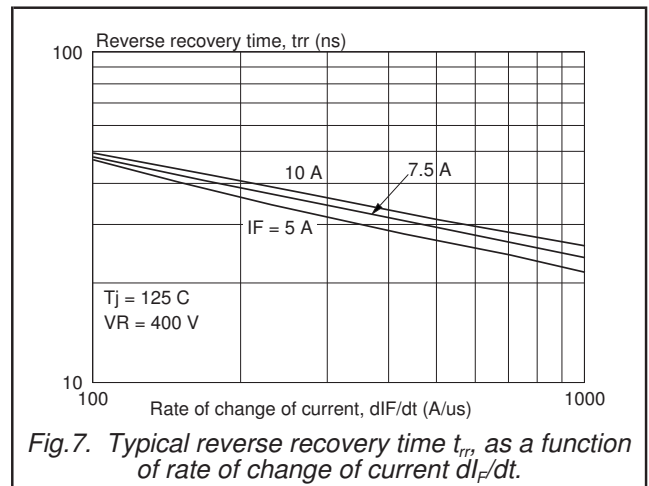
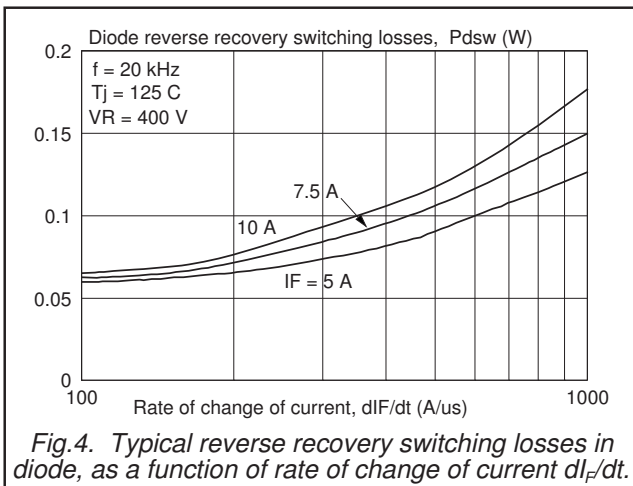
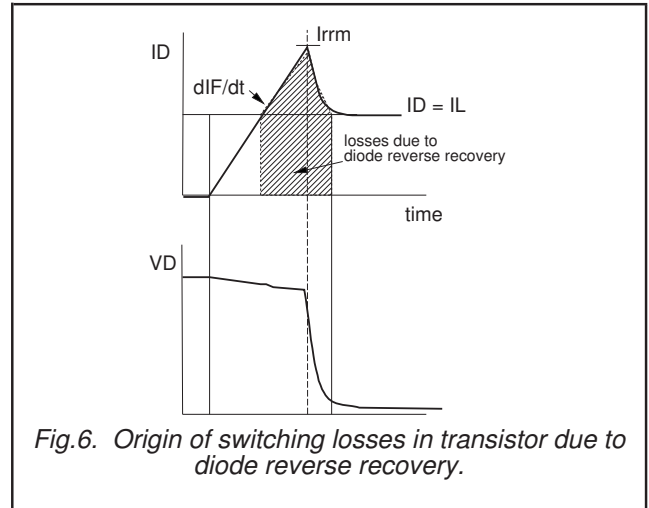
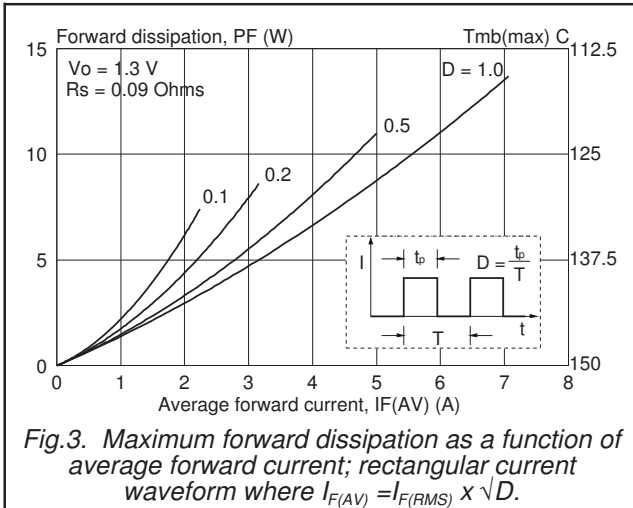
$T_j = 25\text{ }^\circ\text{C}$ unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_F	Forward voltage	$I_F = 5\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.4	1.75	V
		$I_F = 10\text{ A}; T_j = 150\text{ }^\circ\text{C}$	-	1.75	2.2	V
		$I_F = 5\text{ A};$ $V_R = 600\text{ V}$	-	2.0	2.9	V
I_R	Reverse current	$V_R = 500\text{ V}; T_j = 100\text{ }^\circ\text{C}$	-	9	100	μA
			-	0.9	3.0	mA
t_{rr}	Reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}$	-	30	50	ns
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}; V_R = 400\text{ V};$ $dI_F/dt = 500\text{ A}/\mu\text{s}$	-	19	-	ns
t_{rr}	Reverse recovery time	$I_F = 5\text{ A}; V_R = 400\text{ V};$ $dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 100\text{ }^\circ\text{C}$	-	25	30	ns
I_{rrm}	Peak reverse recovery current	$I_F = 5\text{ A}; V_R = 400\text{ V};$ $dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	0.7	3	A
I_{rrm}	Peak reverse recovery current	$I_F = 5\text{ A}; V_R = 400\text{ V};$ $dI_F/dt = 500\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}$	-	8	11	A
V_{fr}	Forward recovery voltage	$I_F = 10\text{ A}; dI_F/dt = 100\text{ A}/\mu\text{s}$	-	9	11	V



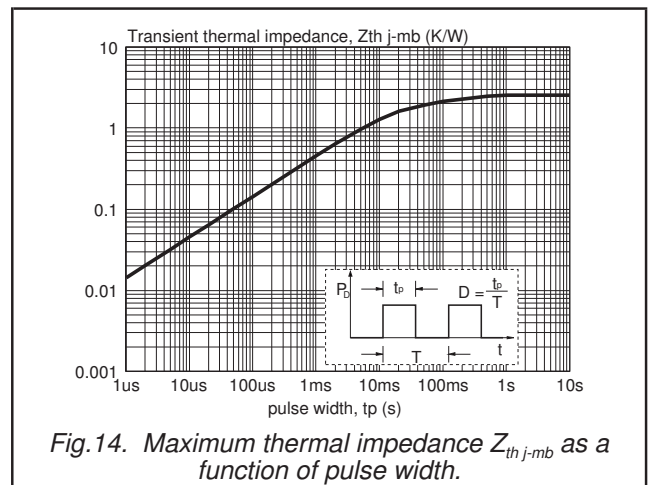
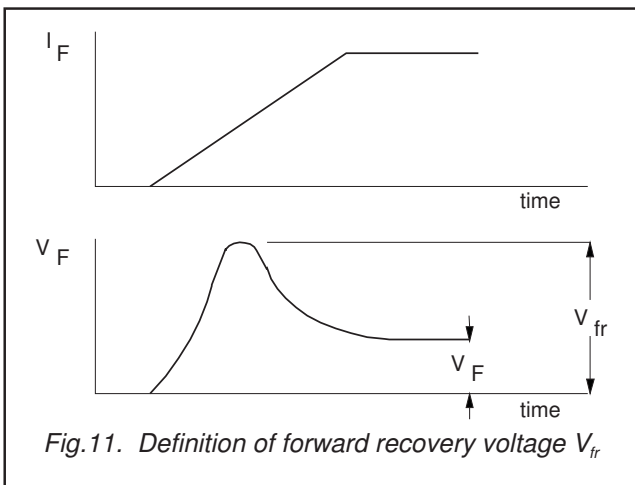
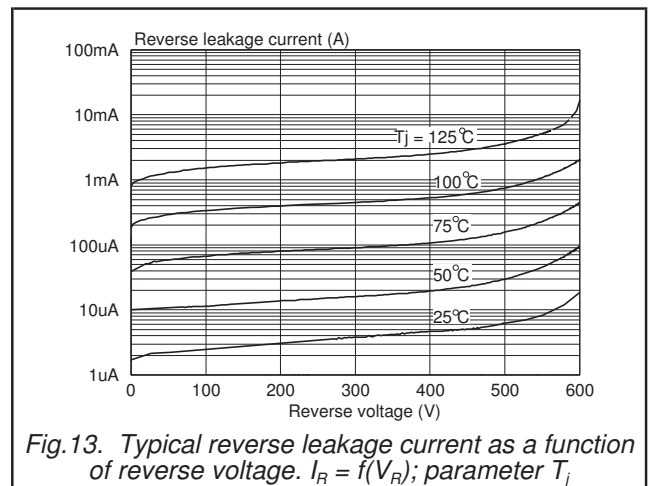
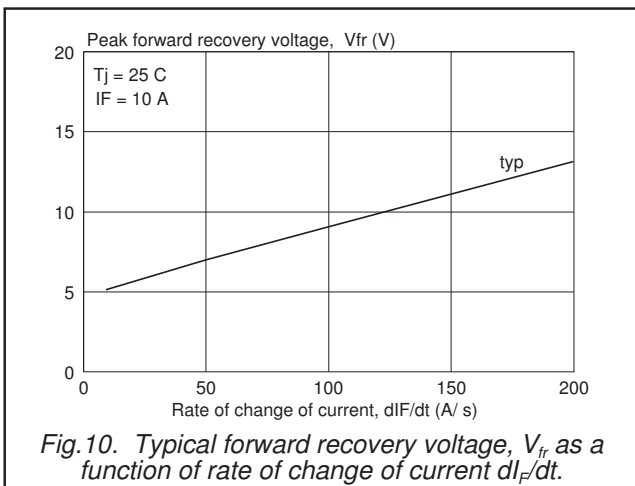
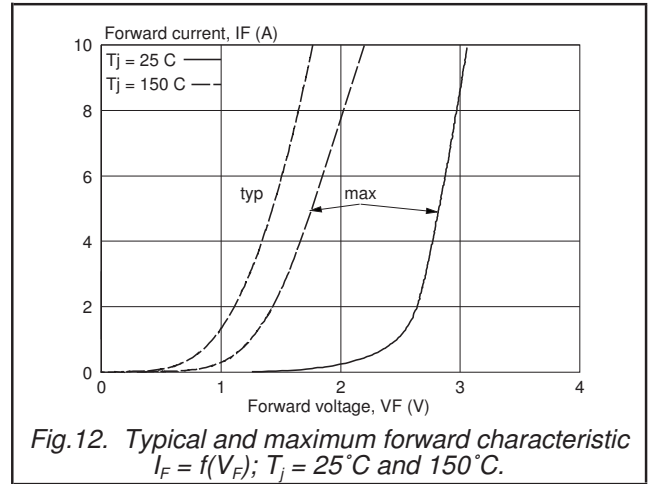
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MECHANICAL DATA

Dimensions in mm Plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220

SOD59

Net Mass: 2 g

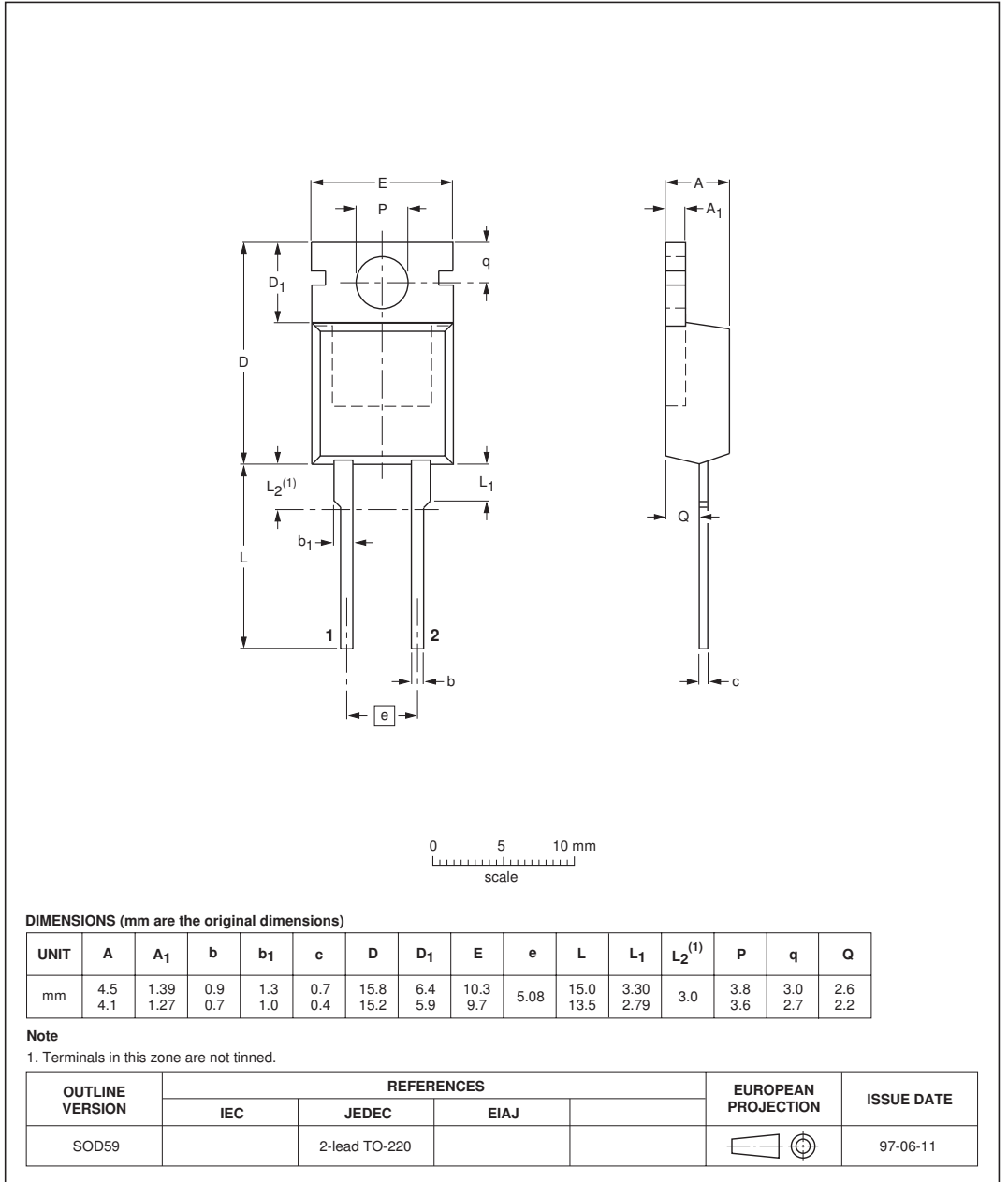


Fig.15. TO220AC; pin 1 connected to mounting base.

Notes

1. Refer to mounting instructions for TO220 envelopes.
2. Epoxy meets UL94 V0 at 1/8".

Legal information

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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